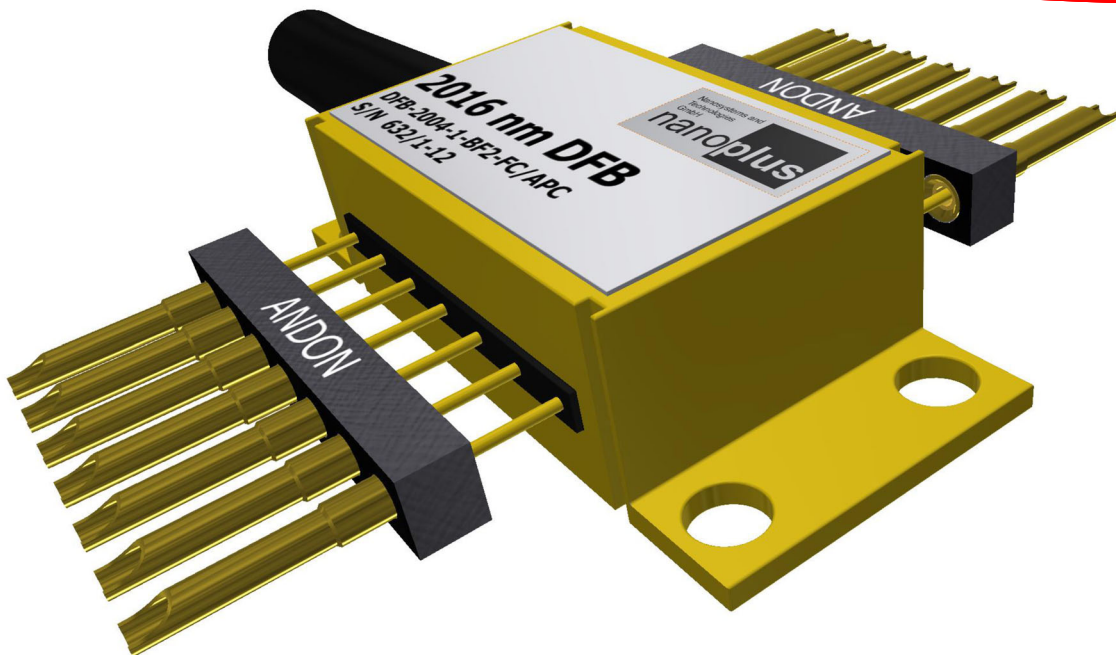


High-Reliability Optoelectronic Sensor Sockets for Nanoplus GmbH

Nanosystems and
Technologies
GmbH

nanoplus



Featuring Andon's Unique SenstacTM Contact

Nano Plus GmbH						
Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type		Pin Ø [in]	Figure Number	Page Number
		Thru-Hole	Surface Mount			
TO5	R200-0808-01T-XXX-R27-L14	75S	265S	.018	4	1
TO5.6	R080-0403-01N-XXX-R27-L14	274K	281K	.018	1	1
TO66	F325-1009-04-XXX-R27-L14	295V	439V	.030	2	1
TO 8mm	R375-SP06-02T-XXX-R27-L14	75S	265S	.018	5	1
TO 9mm	R100-0403-01T-XXX-R27-L14	75S	265S	.018	3	1
14 Pin-Butterfly	(2) 405-0707-01-XXX-R27-L14	556P28	-	.018	6	1

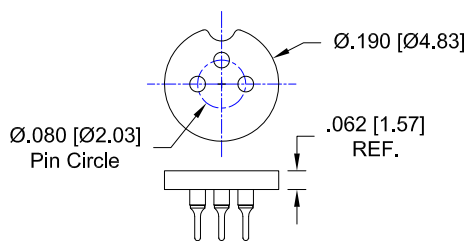


Fig. 1

Thru-Hole: R080-0403-01N-**274K**-R27-L14
Surface Mount: R080-0403-01N-**281K**-R27-L14

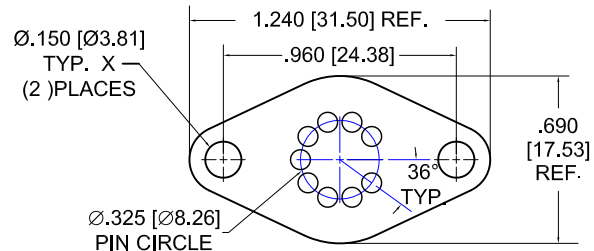


Fig. 2

Thru-Hole: F325-1009-04-**295V**-R27-L14
Surface Mount: F325-1009-04-**439V**-R27-L14

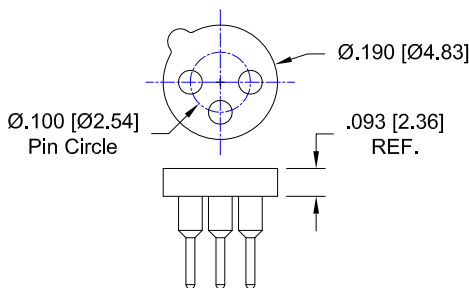


Fig. 3

Thru-Hole: R100-0403-01T-**75S**-R27-L14
Surface Mount: R100-0403-01T-**265S**-R27-L14

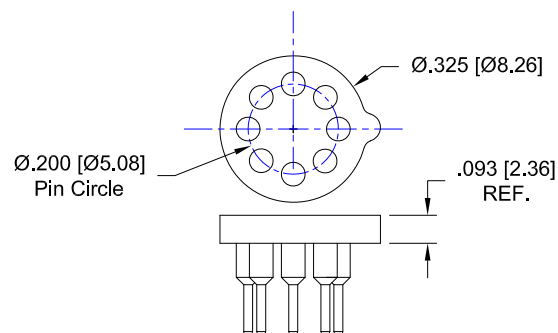


Fig. 4

Thru-Hole: R200-0808-01T-**75S**-R27-L14
Surface Mount: R200-0808-01T-**265S**-R27-L14

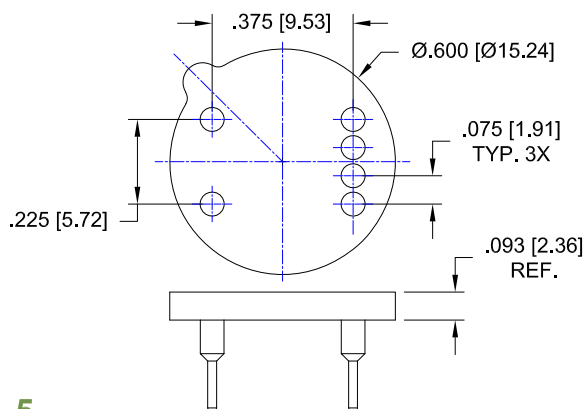


Fig. 5

Thru-Hole: R375-SP06-02T-**75S**-R27-L14
Surface Mount: R375-SP06-02T-**265S**-R27-L14

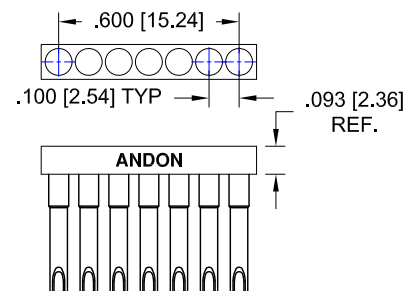


Fig. 6

Solder-Cup: (2) 405-0707-01-**556P28**-R27-L14

NANOPLUS GmbH						
Nanoplus GmbH Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type		Pin Ø [in]	Figure Number	Page Number
TO66	F325-1009-04-XXX-R27-L14-HS1	Thru-Hole	Surface Mount	.030	7	2

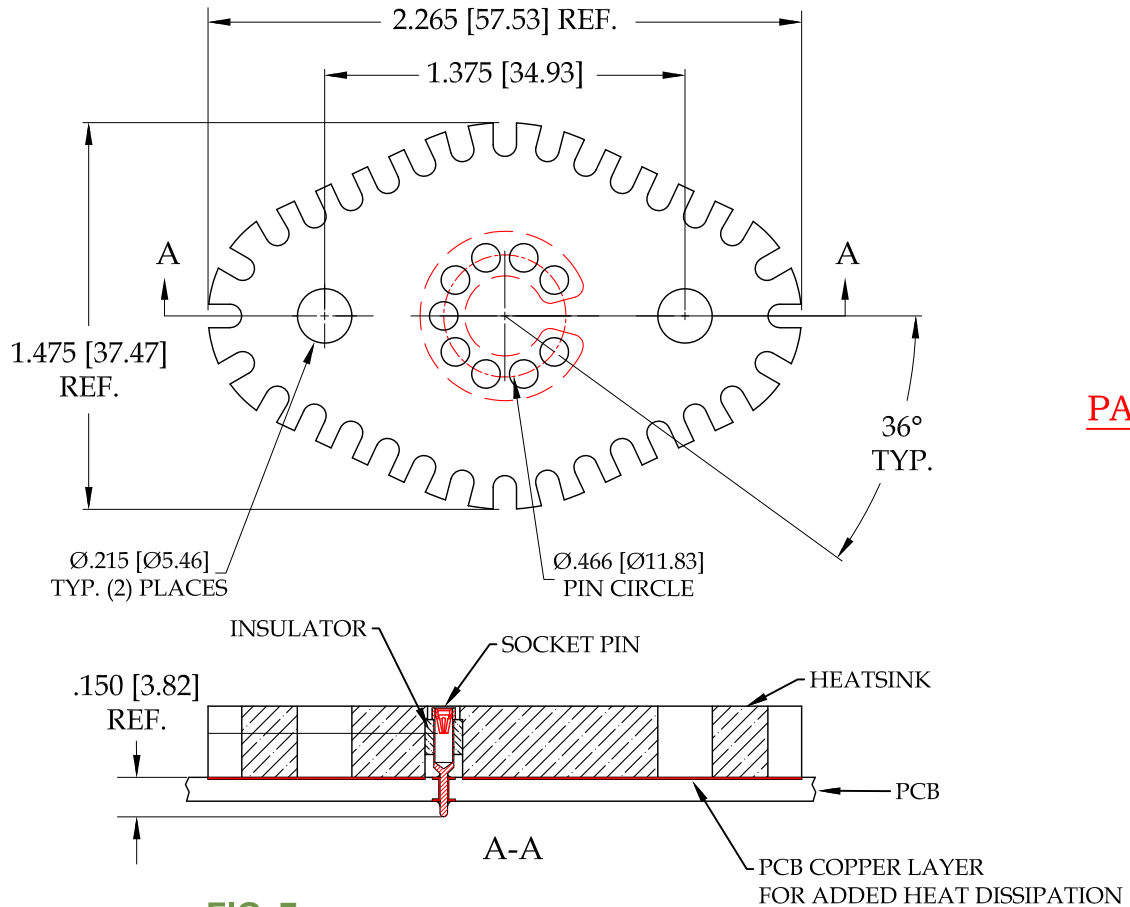
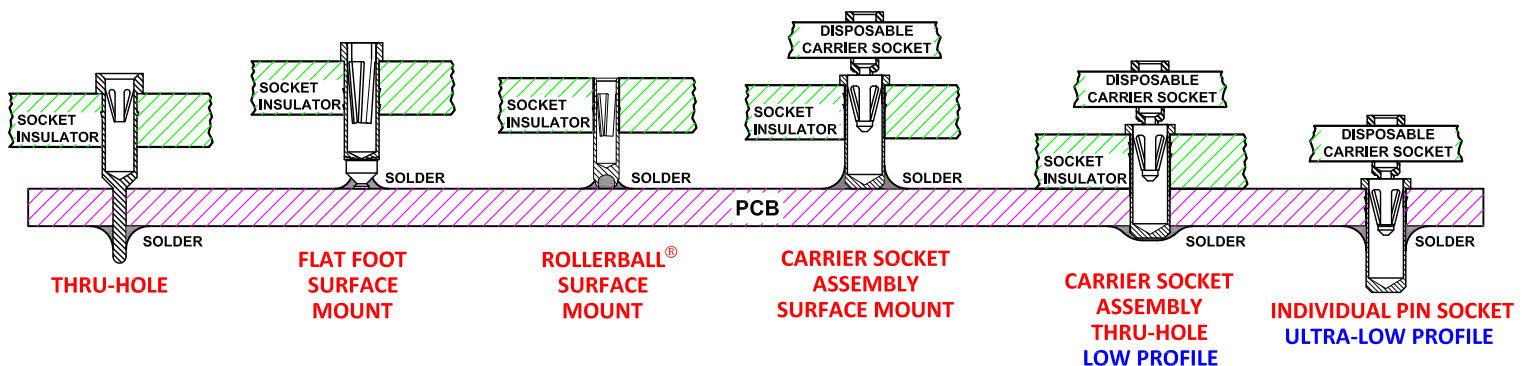


FIG. 7

Thru-Hole: F325-1009-04-75P28-R27-L14-HS1

Socket & Terminal Mounting Options

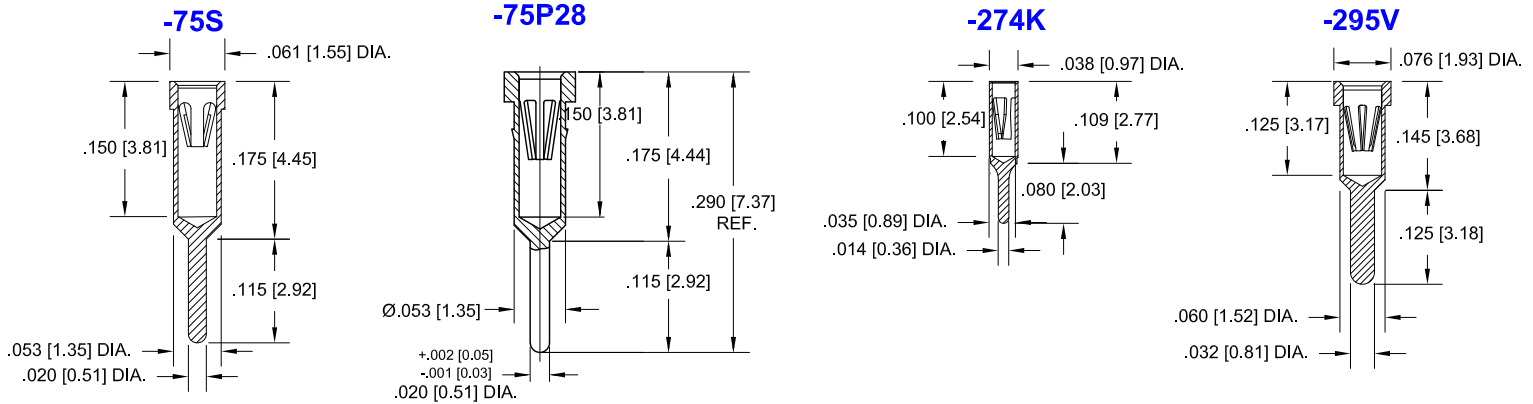


NANOPLUS GmbH Continued

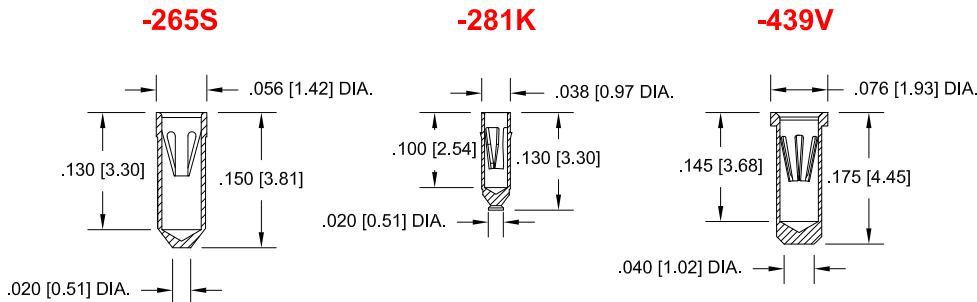
Socket Terminal Details

Cross Section View Shown Units: in [mm]

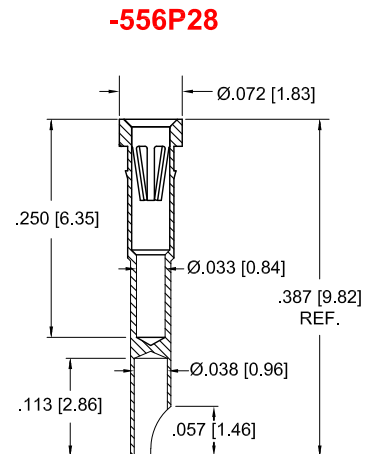
THRU HOLE OPTION



SURFACE MOUNT OPTION



SOLDER CUP OPTION



Technical Information

Material:

Insulator: Hi-Temp UL 94V-O
 Terminal: Brass, per ASTM-B16
 Contact: BeCu, Per ASTM-B194

Plating: RoHS COMPLIANT

R27 TERMINAL: GOLD / CONTACT: GOLD

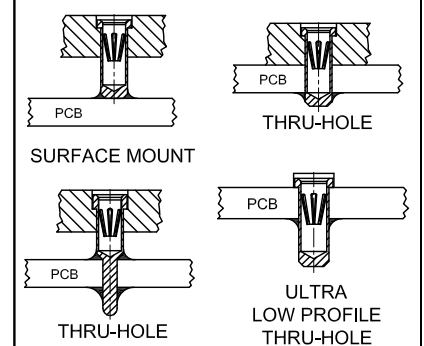
R17 TERMINAL: TIN / CONTACT: GOLD

OTHER PLATINGS AVAILABLE

Terminal Acceptance and Forces

Thru Hole Terminals				Surface Mount Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	Surface Mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
-274K	Ø.018 [Ø0.46]	1.24 oz Max.	0.50 oz Min	-281K	Ø.018 [Ø0.46]	1.24 oz Max.	0.50 oz Min
-75S	Ø.018 [Ø0.46]	9.00 oz Max.	2.00 oz Min	-265S	Ø.018 [Ø0.46]	9.00 oz Max.	2.00 oz Min
-75P28	Ø.018 [Ø0.46]	0.70 oz Max.	0.35 oz Min	-439V	Ø.030 [Ø0.76]	13.23 oz Max.	3.53 oz Min
-295V	Ø.018 [Ø0.46]	13.23 oz Max.	3.53 oz Min	Solder Cup Terminals			
				-556P28	Ø.018 [Ø0.46]	0.70 oz Max.	0.35 oz Min

MOUNTING OPTIONS



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RoHS Compliant

Andon Proprietary Information

*Sockets are not drawn to scale Nanoplus GmbH 03/22/2024

ANDON ELECTRONICS CORPORATION
 4 Court Drive, Lincoln RI 02865, United States of America

www.andonelectronics.com or www.andonelect.com

Phone 401-333-0388 Fax 401-333-0287

Email Info@andonelect.com

For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies designed to your pin layout.



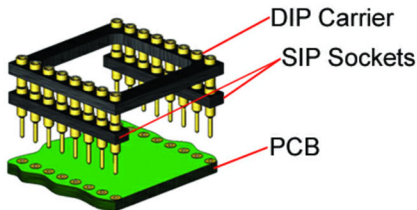
Phase 2:
Place carrier assemblies onto PCB; run through your soldering process.



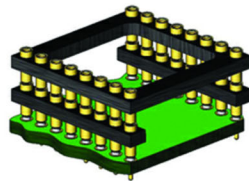
Phase 3:
Remove carrier and plug in your device; discard carrier.

DIP

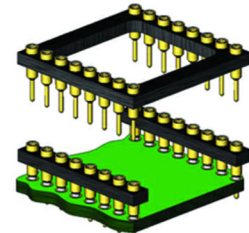
Before Soldering



During Soldering

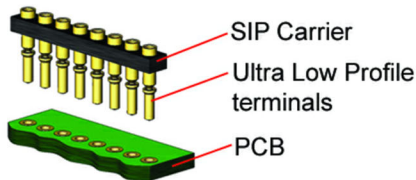


After Soldering

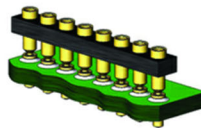


ULTRA-LOW PROFILE SIP

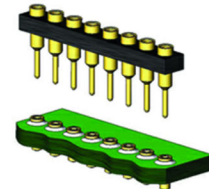
Before Soldering



During Soldering

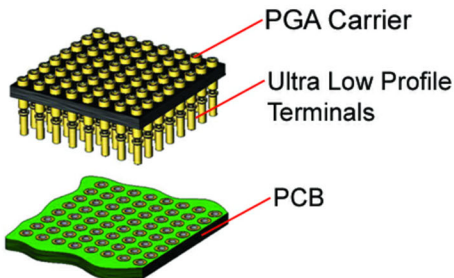


After Soldering

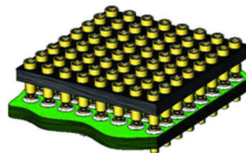


ULTRA-LOW PROFILE PGA

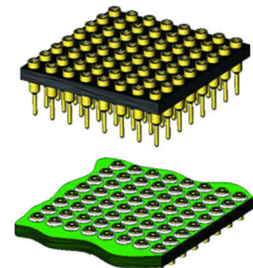
Before Soldering



During Soldering

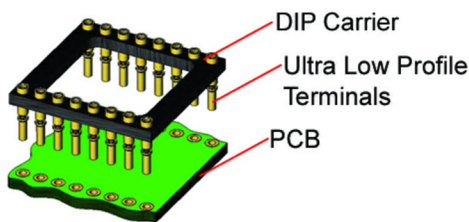


After Soldering

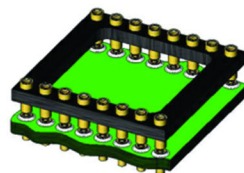


ULTRA LOW PROFILE DIP

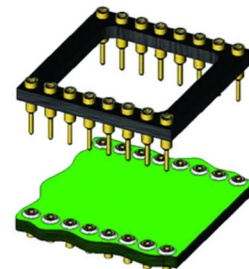
Before Soldering



During Soldering



After Soldering



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